

Amendments to the Specification:

Please replace the first paragraph, immediately following the title, on page 1 with the following amended paragraph.

This is a division of Patent Application serial number ~~08/239,375~~ 08/518,182, filing date ~~5/6/94~~ 08/23/95, Composite Bump Bonding, ~~assigned to the same assignee as the present invention, now U.S. Pat. No. 6,365,500 B1, which is a~~ Continuation of Patent Application serial number 08/239,375, filing date 5/6/94, now abandoned.

On page 1 please replace the paragraph immediately following the heading RELATED PATENT APPLICATIONS with the following amended paragraph.

(1) (E83-0003), Serial No. 08/239,424, filed May 6, 1994, entitled Composite Bump Structure and Methods of Fabrication assigned to the same assignee, now U.S. Patent No. 5,393,697 ~~5,393,679~~.

(2) (E83-0004), Serial No. 08/239,380, filed May 6, 1994, entitled Composite Bump Flip Chip Bonding assigned to the same assignee, now U.S. Patent No. 5,431,328.